**Product data sheet** 

## 1. General description

Silicon Carbide Schottky diode in a TO263 (D2PAK) plastic package, designed for high frequency switched-mode power supplies.





### 2. Features and benefits

- · Highly stable switching performance
- High forward surge capability I<sub>FSM</sub>
- · Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- · Reduced losses in associated MOSFET
- Reduced EMI
- · Reduced cooling requirements
- RoHS compliant

## 3. Applications

- · Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- · Motor Drives

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit	
Absolute	maximum rating						
$V_{RRM}$	repetitive peak reverse voltage			6	50		V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5 ; square-wave pulse; T <sub>mb</sub> ≤ 125 °C; Fig. 1; Fig. 2; Fig. 3	6		А		
T <sub>j</sub>	junction temperature		175		°C		
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static ch	aracteristics						
$V_{F}$	forward voltage	I <sub>F</sub> = 6 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.5	1.7	V
		I <sub>F</sub> = 6 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.8	2.1	V
Dynamic	Dynamic characteristics						
Q <sub>r</sub>	recovered charge	$I_F = 6 \text{ A}; dI_F/dt = 500 \text{ A/}\mu\text{s}; V_R = 400 \text{ V};$ $T_j = 25 \text{ °C}; Fig. 7$		-	9	-	nC

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected		v 14 a
2	K	cathode		K — A 001aaa020
3	А	anode		
mb	К	mounting base; connected to cathode	10-263 (D2PAK)	

<sup>[1]</sup> It is not possible to connect to pin 2 of the TO263 package.

# 6. Ordering information

**Table 3. Ordering information** 

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
NXPSC06650B	TO263	NXPSC06650B6J	Reel	800	TO263N	26-Sep-2016

# 7. Marking

#### Table 4. Marking codes

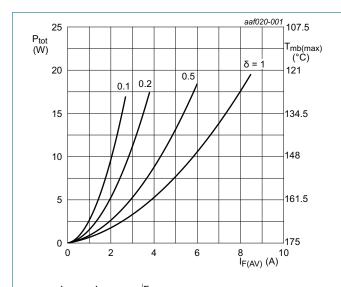
Type number	Marking codes
NXPSC06650B	NXPSC 06650B

# 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		650	V
$V_{\text{RWM}}$	crest working reverse voltage		650	V
$V_R$	reverse voltage	DC	650	V
I <sub>F(AV)</sub>	average forward current	$δ$ = 0.5; square-wave pulse; $T_{mb} \le 125$ °C; Fig. 1; Fig. 2; Fig. 3	6	А
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 125 °C; square-wave pulse	12	А
I <sub>FSM</sub>	non-repetitive peak	$t_p = 10 \text{ ms; } T_{j(init)} = 25 \text{ °C; sine-wave pulse}$	36	Α
	forward current	t <sub>p</sub> = 10 μs; T <sub>j(init)</sub> = 25 °C; square-wave pulse	310	А
l <sup>2</sup> t	I <sup>2</sup> t for fusing	sine-wave pulse; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 10 \text{ ms}$	6.48	A <sup>2</sup> s
T <sub>stg</sub>	storage temperature		-55 to 175	°C
T <sub>j</sub>	junction temperature		175	°C



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$  $V_o = 0.444 \text{ V; } R_s = 0.2192 \Omega$ 

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

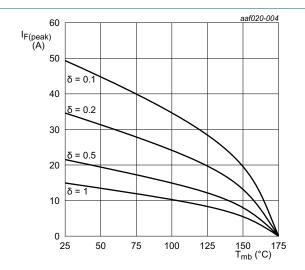
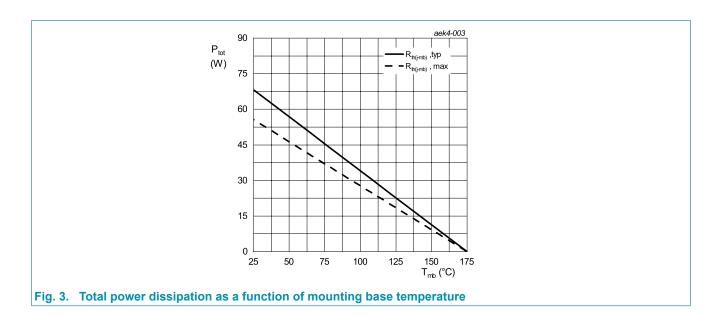


Fig. 2. Current derating as a function of mounting base temperature



### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	with heatsink compound; Fig. 4	-	2.2	2.7	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

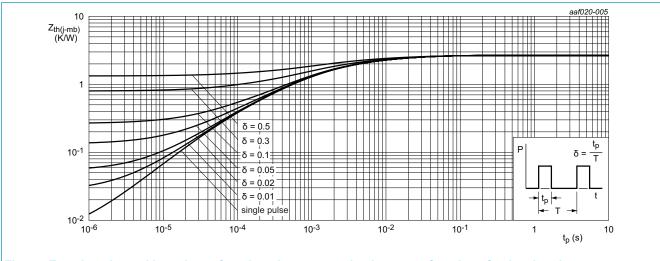
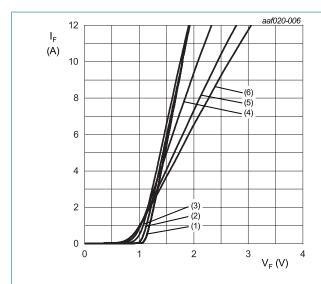


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

### 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics		<u> </u>	•	•	•
V <sub>F</sub>	forward current	I <sub>F</sub> = 6 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>	-	1.5	1.7	V
		I <sub>F</sub> = 6 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>	-	1.8	2.1	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	-	40	μA
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>	-	-	160	μA
Dynamic	characteristics			'		
$Q_r$	recovered charge	$I_F = 6 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	9	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C	-	190	-	pF
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>j</sub> = 25 °C	-	30	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C	-	29	-	pF
E <sub>as</sub>	non-repetitive	I <sub>R</sub> = 4.25 A; L = 5 mH; T <sub>j(init)</sub> = 25 °C	45	-	-	mJ
	avalanche energy					



 $V_o = 0.444 \text{ V}; R_s = 0.2192 \Omega$ 

(1) T<sub>i</sub> = -55 °C; typical values

(2)  $T_j = 0$  °C; typical values

(3) T<sub>j</sub> = 25 °C; typical values (4) T<sub>j</sub> = 100 °C; typical values

(5)  $T_i = 150$  °C; typical values

(6)  $T_i = 175$  °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

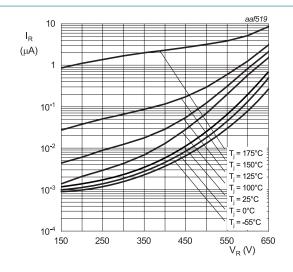


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

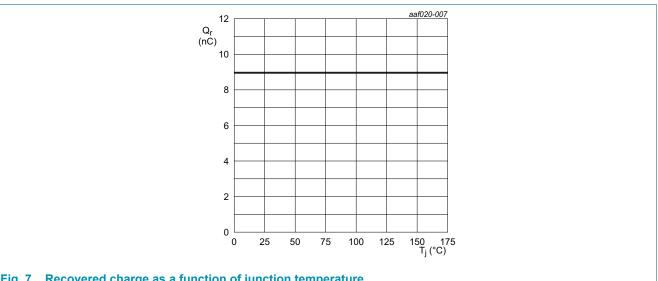
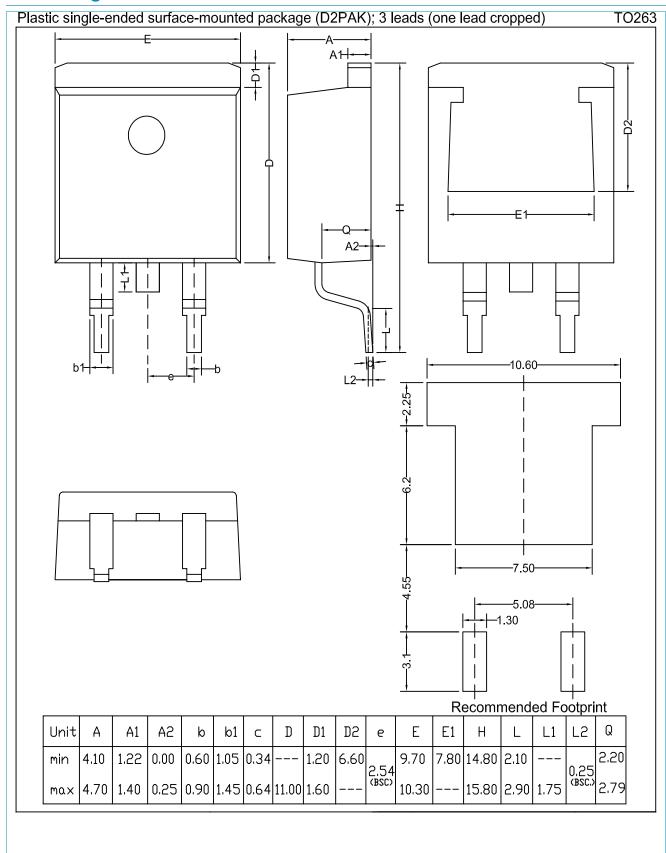


Fig. 7. Recovered charge as a function of junction temperature

# 11. Package outline



### 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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